

## PATENT ASSIGNMENT COVER SHEET

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EPAS ID: PAT4102789

<b>SUBMISSION TYPE:</b>	NEW ASSIGNMENT
<b>NATURE OF CONVEYANCE:</b>	RELEASE OF SECURITY INTEREST
<b>CONVEYING PARTY DATA</b>	
<b>Name</b>	<b>Execution Date</b>
BANK OF AMERICA, N.A.	10/18/2016
<b>RECEIVING PARTY DATA</b>	
<b>Name:</b>	SUPERIOR BULK LOGISTICS, INC.
<b>Street Address:</b>	711 JORIE BLVD.
<b>Internal Address:</b>	#101
<b>City:</b>	OAK BROOK
<b>State/Country:</b>	ILLINOIS
<b>Postal Code:</b>	60523
<b>PROPERTY NUMBERS Total: 1</b>	
<b>Property Type</b>	<b>Number</b>
Patent Number:	7115170
<b>CORRESPONDENCE DATA</b>	
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<b>ATTORNEY DOCKET NUMBER:</b>	013030.0003
<b>NAME OF SUBMITTER:</b>	ARVID VON TAUBE
<b>SIGNATURE:</b>	/Arvid von Taube/
<b>DATE SIGNED:</b>	10/18/2016
<b>Total Attachments: 3</b>	
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## RELEASE PATENT SECURITY INTERESTS

This Release of Patent Security Interests is dated as of October 18, 2016. Reference is hereby made to that certain Notice of Grant of Security Interest in Patents, dated as of December 12, 2011 (the "*Agreement*"), from SUPERIOR BULK LOGISTICS, INC., a Delaware corporation (the "*Grantor*"), in favor of BANK OF AMERICA, N.A., as Collateral Agent (the "*Grantee*"), recorded with the United States Patent and Trademark Office on December 16, 2011 at Reel/Frame No. 027397/0420.

For good and valuable consideration, receipt and sufficiency of which are hereby acknowledged, the Grantee hereby irrevocably releases its security interests in and collateral assignment of, and reassigns, grants and conveys to the Grantor, without any representation, warranty, recourse or undertaking by the Grantee except as expressly set forth below, all of its right, title and interest, if any, in and to:

(i) Each patent, patent registration and patent application listed on Schedule A hereto (including all reissues, continuations and extensions thereof), and all of the goodwill of the business connected with the use of, and symbolized by, each such patent, patent registration and patent application; and

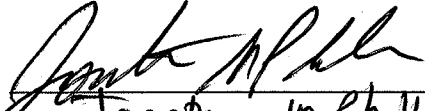
(ii) All proceeds of the foregoing, including without limitation any claim by Grantor against third parties for damages by reason of past, present or future infringement or dilution of any patent, patent registration, or patent application listed on Schedule A hereto or by reason of injury to the goodwill associated with any such patent, patent registration or patent application, in each case together with the right to sue for and collect said damages.

The Grantee hereby represents and warrants to the Grantor that it has not, directly or indirectly, by operation of law or otherwise, assigned, transferred or conveyed any of its rights or obligations with respect to the Agreement or any patent, patent registration, or patent application listed on Schedule A hereto.

[SIGNATURE PAGE TO FOLLOW]

IN WITNESS WHEREOF, the undersigned has caused this Release of Patent Security Interests to be duly executed by its duly authorized officer as of the day and year first above written.

BANK OF AMERICA, N.A., as Collateral Agent

By   
Name: Jonathan M. Phillips  
Title: Senior Vice President

[SIGNATURE PAGE TO RELEASE OF PATENT SECURITY INTERESTS—SUPERIOR BULK LOGISTICS, INC.]

PATENT  
REEL: 040050 FRAME: 0098

**SCHEDULE A  
TO  
RELEASE OF PATENT SECURITY INTERESTS**

**I. REGISTERED PATENT**

- A. Superior Bulk Logistics, Inc.'s patent for a portable bulk product melt system that is registered with the United States Patent and Trademark Office on October 3, 2006, U.S. Patent No. 7,115,170.